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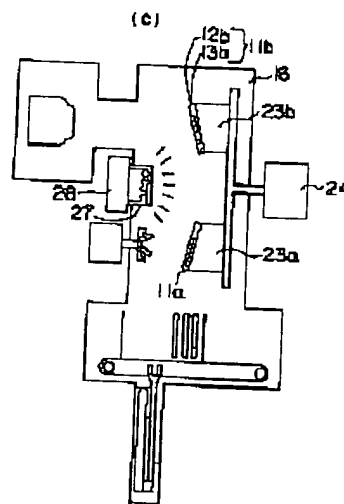
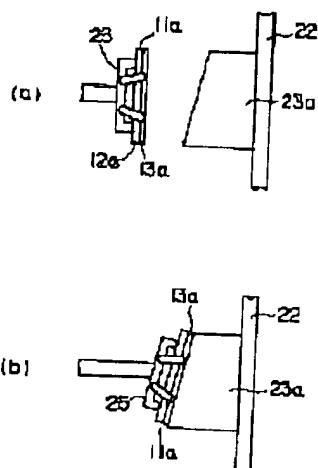
(74) Representative:

(54) PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

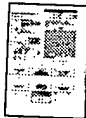
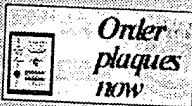
(57) Abstract:

PURPOSE: To provide a method for removing particles from a semiconductor production system or from the surface of a semiconductor substrate or a reticle more easily and positively with no adverse effect.

CONSTITUTION: Particle eliminators 11a, 11b are bonded, at the adhesive layers 13a, 13b thereof, to bases 23a, 23b for mounting a substrate. Subsequently, the



particle eliminators 11a, 11b are peeled off the substrate holding bases 23a, 23b thus removing the particles from the surfaces thereof.



JP7142440A2: PARTICLE REMOVING METHOD AND SEMICONDUCTOR PRODUCTION SYSTEM HAVING PARTICLE REMOVING MEANS

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Country: JP Japan

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Applicant(s): FUJITSU LTD

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Issued/Filed Dates: June 2, 1995 / Nov. 19, 1993

Application Number: JP1993000291013

IPC Class: **H01L 21/304; B08B 7/00;**

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